

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE PATENT APPLICATION OF: **JE A GUN PARK , ET AL.**  
SERIAL NO.: **10/540,992**  
ATTORNEY DOCKET NO.: **061063-0316598**  
FILING DATE: **June 5, 2006**  
CONFIRMATION NO.: **9014**  
ART UNIT: **1792**  
EXAMINER: **ANGADI, Maki A.**  
FOR: **CHEMICAL-MECHANICAL-POLISHING SLURRY COMPOSITION, METHOD FOR PLANARIZING SURFACE OF SEMICONDUCTOR DEVICE USING THE SAME, AND METHOD FOR CONTROLLING SELECTION RATIO OF SLURRY COMPOSITION**

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**RESPONSE TO NON-FINAL OFFICE ACTION**

**Mail Stop Amendment**  
**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

Sir:

In response to the Non-Final Office Action mailed August 13, 2008, the date for responding being extended by a one-month extension of time to December 13, 2008, please amend the above-identified application as follows:

**Amendments** to the claims begin on page 2 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.